

VUE 400-P SCANNING ACOUSTIC MICROSCOPE

Semiconductor Package Failure Analysis
voids · disbonds · cracks · delamination · internal defects

Customer Interface

Dual 22" HD LED Monitors

Fixtures

Tray Fixture

Instrumentation

Digital Pulser Receiver
Ultrasonic Digitizer (Max 12 GHz)

User Experience Elements

Dual JEDEC Trays
HD LED Lighting
ESD or Stainless Steel Tank

Maintenance Free Scan Axis

Motor:

Max Velocity:

Accuracy & Repeatability:

Scan Envelope:

Low Maintenance Step Axis:

Step Envelope

Low Maintenance Focus Axis:

Focus Envelope

Dimensions:

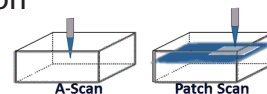
0.9 m x 0.86 m x 1.18 m (W/D/H)
227 kg

Quad Linear Servo

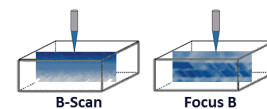
1500 mm/s

+/- 0.5 micron

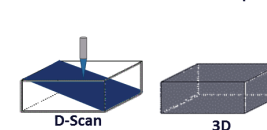
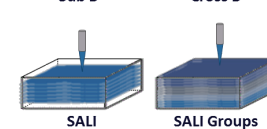
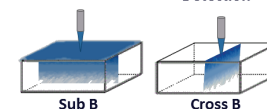
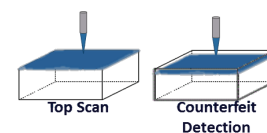
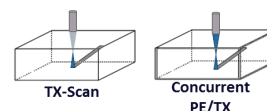
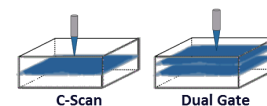
380 mm



350 mm



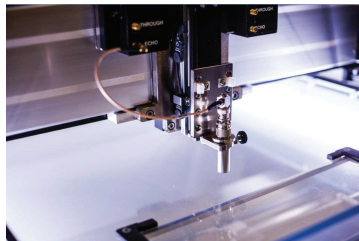
50 mm



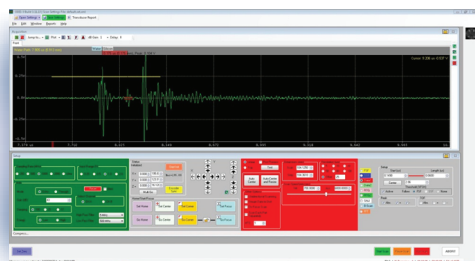
VUE 400-P SCANNING ACOUSTIC MICROSCOPE

Included Software Modes:

- Basic (user friendly)
- Advanced (detailed analysis)
- Production (automated scanning)
- Off-line Analysis (virtual scanning)



OKOS Digital Imaging System (ODIS)



VUE 400-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities. ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback. It includes both time domain and frequency domain imaging in real-time. Advanced analysis is provided through quantitative tools for measurement and classification of parts.

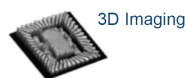
The Analysis version of ODIS allows non-scanning computers to virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review. Supplied with your choice of Windows 7 or 10.

- Counterfeit Detection
- Product Inspection
- Product Reliability
- Quality Control
- Process Validation
- Failure Analysis
- Vendor Qualification
- R&D

Application Specific Transducers

for the highest quality resolution.

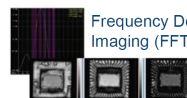
Multiple transducer design for enhanced scan capability.



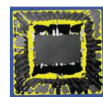
3D Imaging



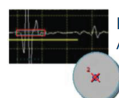
C-scan with Multi-gate
SALI & SALI Groups



Frequency Domain
Imaging (FFT)



Advanced Time-of-Flight &
Thickness Measurements



Real-time A-scan &
A-scan Capture



Void Gating
(real-time)



Cluster Analysis
(post processing)



Threshold Mapping
(post processing)



B-scan & SLICE